

Without Knob Type RK08H Series

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PRINT

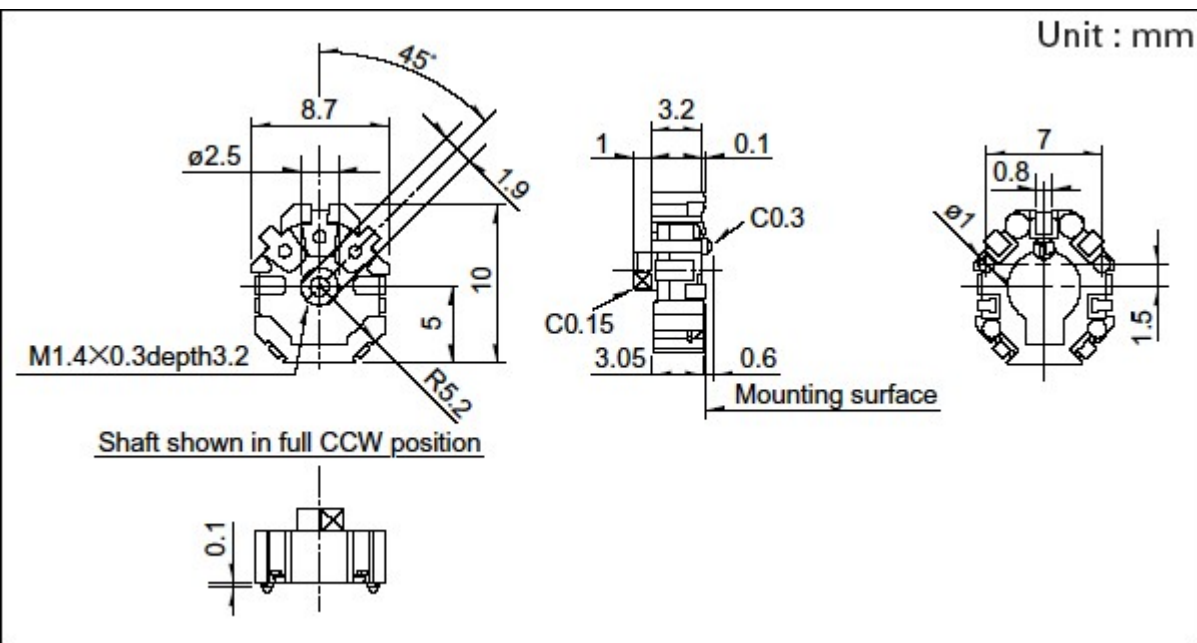
Part number		RK08H113003G
Number of resistor elements		Single-unit
Mounting direction		Vertical type
Length of the shaft		1 mm
Center detent		Without
Total resistance		50kΩ
Resistance taper		1B
Soldering		Reflow
Operating temperature range		-10 to +60
Electrical Performance	Total resistance tolerance	±30%
	Rated power	0.03W
	Maximum operating voltage	50V AC, 20V DC
	Maximum attenuation	80dB min.
	Residual resistance	50Ω or less
Mechanical Performance	Total rotational angle	200°±10°
	Rotational torque	0.5 to 10mN·m
	Stopper strength	0.1N·m
	Push-pull strength	10N
Durability	Operating life	10,000 cycles
Minimum order unit (pcs.)	Japan	1,000
	Export	1,000

3D CAD (STEP)

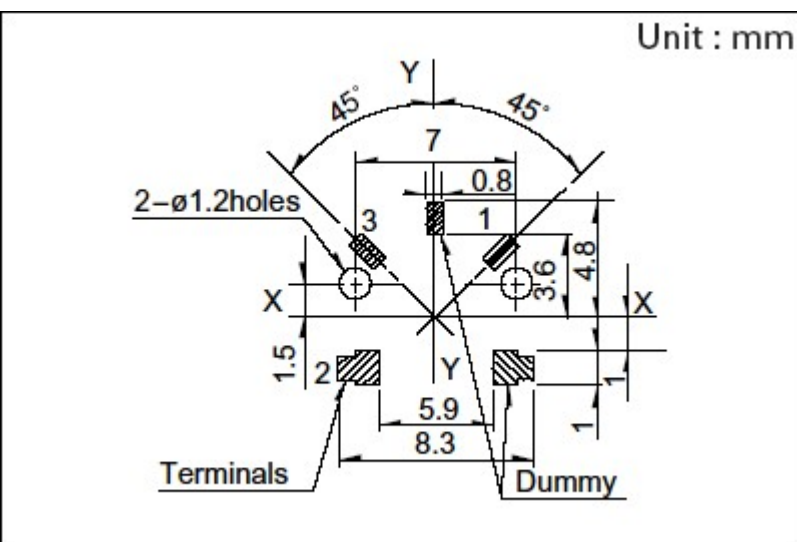
Certificate of Compliance to RoHS regulations



Dimensions

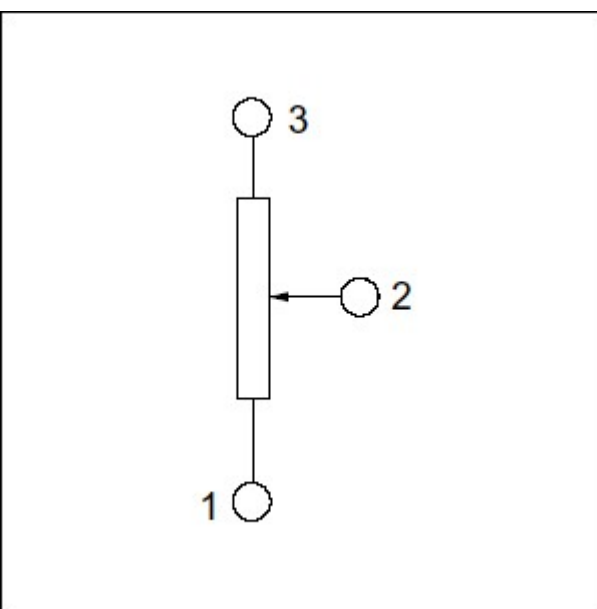


Mounting Hole Details



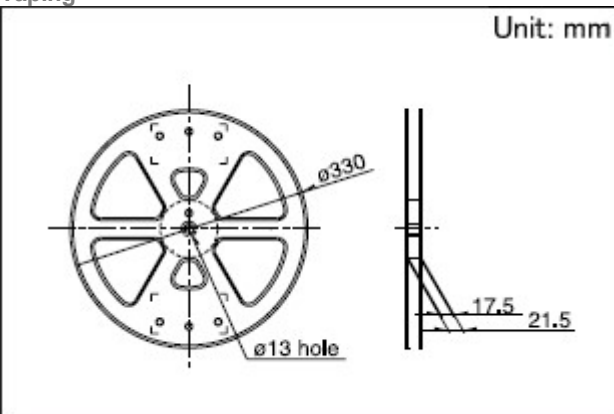
1. Keep the DUMMY terminal open in the circuit.
2. Shaded areas are solder lands.

Circuit Diagram



Packing Specifications

Taping



Number of packages (pcs.) 1 reel 1,000

1 case / Japan 4,000

1 case / export packing 4,000

Tape width (mm) 16

Export package measurements (mm) 397×401×139

Soldering Conditions

Example of Reflow Soldering Condition

1. Heating method

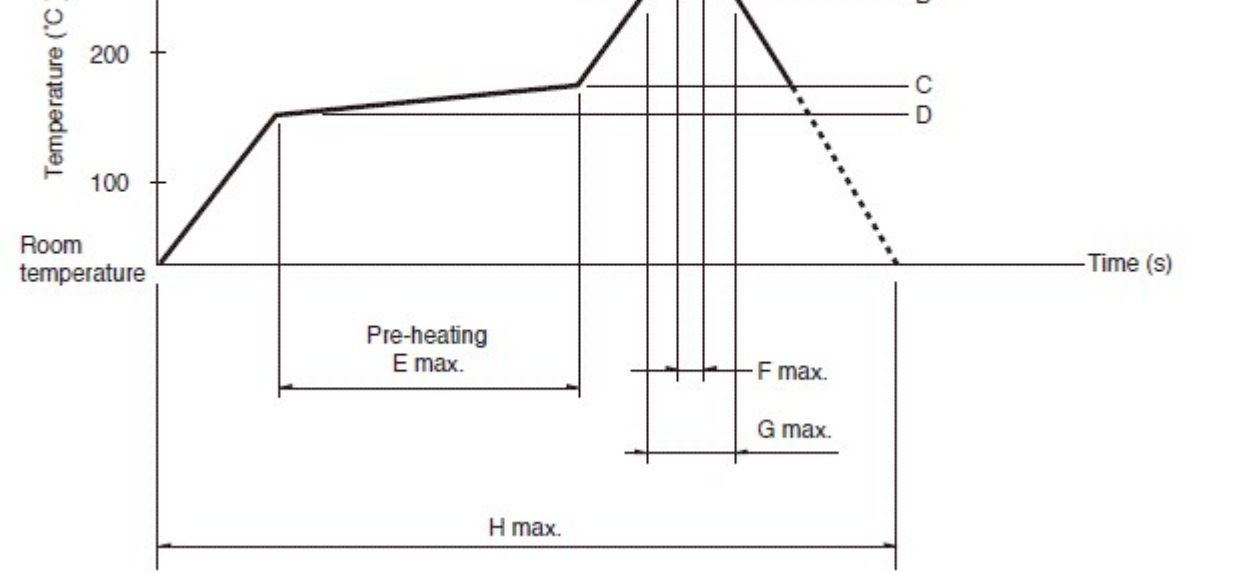
Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile





A	B	C	D	E	F	G	H	No. of reflows
250	200	150	150	2 min.	3s	40s	4 min.	2 time max.

1. When using an infrared reflow oven, solder may sometimes not be applied. Be sure to use a hot air reflow oven or a type that uses infrared rays in combination with hot air.
2. The temperatures given above are the maximum temperatures at the terminals of the potentiometer when employing a hot air reflow method. The temperature of the PC board and the surface temperature of the potentiometer may vary greatly depending on the PC board material, its size and thickness. Ensure that the surface temperature of the potentiometer does not rise to 250°C or greater.
3. Conditions vary to some extent depending on the type of reflow bath used. Be sure to give due consideration to this prior to use.

Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).
3. Products other than those listed in above products are also available. Please contact us for details.
4. Dip soldering can be applied to the above products. For dip soldering applications, specify separately as "dip soldering applicable product". Back-to-back mounting types are excluded.
5. We recommend print boards with a thickness of 0.8mm to 1.2mm. For 1.6mm thickness board applications, please contact us.

Inquiries about Products

